	1	1. A package article for removably accepting a fiber
/	% ² ∕	optic cable, said package article operatively connected to a
SW	\$\frac{1}{2} \int \frac{1}{2}	host card, comprising:
•	4	a laminate for supporting optoelectronic
	5	components;
	6	an amplifier die operatively connected to and
	7	supported by said laminate for amplifying electrical
գրու գրոր գրու գրու գրոր այիր լիներ (¹⁷ 12 Կուսու Կում Կորոլ IP Կուսու Կ Ա Կորո Մորո	8	signals;
	9	a flexible circuit electrically connected to and
(M)	10	supported by said laminate for receiving said amplified
The state with the state of the	11	electrical signals from said amplifier die; and
	12	an optoelectronic die electrically connected to
	13	said flexible circuit for receiving said amplified
	14	electrical signals generated by said amplifier die and
	15	for generating optical signals responsive thereto.

2. The packag	ge article for remo	vably accepting a fiber
optic cable operat	ively connected to	host card in
accordance with cla	aim 1, said package	article further
comprising:		

a heatsink carrier operatively connected to said flexible circuit, and attached to said optoelectronic die for removing heat therefrom.

3. The package article for removably accepting a fiber optic cable operatively connected to a host card in accordance with claim 1 said package article further comprising:

an optical subassembly in optical communication with said optoelectonic die for receiving and processing said optical signals therefrom, said optical subassembly comprising an optical coupler and a removable optical connector having an optical cable.

4. An optoelectronic subassembly for accepting optical
signals from a fiber optic cable, said optoelectronic
subassembly being operatively connected to a host card, said
optoelectronic subassembly comprising:

an optoelectronic die for receiving electrical signals and for generating optical signals responsive thereto;

a flexible circuit electrically connected to said optoelectronic die;

an optical coupler optically connected to said optoelectronic die for receiving optical signals therefrom; and

a heatsink carrier operatively connected to said flexible circuit, and attached to said optoelectronic die for removing heat therefrom.

	2	optical signals from a fiber optic cable in accordance with
	3	claim 4, said optoelectronic subassembly further comprising:
	4	an optical connector removably connected to and in
	5	optical communication with said optical coupler; and
	6	a retainer operatively connected to said optical
***	7	coupler and removably connected to said optical
. 16th (I'm)	8	connector for aligning said optical coupler and optical
	9	connector.
	1 72	6. The optoelectronic subassembly for accepting optical signals from a fiber optic cable in accordance with claim 5, wherein said optical connector further comprises an
Har first for	4	optical cable.

5. The optoelectronic subassembly for accepting

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thereto; and

1	7. A package article for removably accepting a fiber		
2	optic cable, said package article operatively connected to		
3	host card, said package article comprising:		
4	a flexible circuit for receiving electrical		
5	signals;		
6	an optoelectronic die operatively connected to		
7	said flexible circuit for receiving said electrical		

a heatsink carrier operatively connected to said flexible circuit, and attached to said optoelectronic die for removing heat therefrom.

signal and for generating optical signals responsive

	1	8. The package article in accordance with claim 7,
	NF.	<pre>further comprising:</pre>
	20 / 20 /	
2	/3	a laminate for supporting optoelectronic
1	4	components;
	5	an amplifier de operatively connected to and
	6	supported by said /aminate for amplifying electrical
	7	signals;
164, (1 ¹¹ 5 tart tarf		
	8	an optical subassembly in optical communication
քրու բրակ բրու, որըս վորի սիսը բնու, գ ^{րու} ն Կուու Կուժ՝ Կուժ։ Ծ՝ Դում։ Ֆ Գրուք Կույն	9	with said optoelectronic die for receiving and
am Amir I Sum Sund 1	10	processing said optical signals therefrom, said optical
	11	subassembly/comprising an optical coupler and a
	12	removable ϕ ptical connector having an optical cable;
	13	and

	14	a retainer operatively connected to said optical
	15	coupler and removably connected to said optical
	16	connector for aligning said optical coupler and optical
	17	connector.

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- 9. A package article for removably accepting a horizontally oriented fiber optic ϕ able, operatively connected to a host card, comprising: a flexible circuit disposed between at least one translating die operatively connected to a laminate, and an optoelectronic die; at least one heatsink carrier; a fiber/optic cable connected to said at least one translating die such that said fiber optic cable exits from said laminate in a direction substantially parallel to a horizontal plane defining an orientation of said laminate; an overmold frame that is supported by said laminate, said overmola frame having a cavity for receiving said flexible circuit, said optoelectronic die and said at least one heatsink carrier; said at least one heatsink carrier being operatively connected to said optoelectronic die; said cavity/of said overmold frame enclosing and securing said at least one heatsink carrier, said optoelectroni¢ die and said flexible circuit.
- 10. The package article in accordance with claim 9, further comprising an adhesive for attaching said flexible circuit to said at least one heat sink carrier and said laminate to said flexible circuit and said optoelectronic die to said at least one heat sink carrier.

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11. The package article in accordance with claim 9, further comprising at least one faraday barrier shield, said overmold frame housing said at least one faraday barrier shield providing RF isolation of said at least one optoelectronic die.

- 12. The package article in accordance with claim 9, further comprising a fiber optic coupling disposed between said optoelectronic die and said at least one fiber optic cable.
- 13. The package article in accordance with claim 12, further comprising a retainer, and wherein said fiber optic coupling disposed between said optoelectronic die and said at least one fiber optic cable is snap connected to said retainer, said retainer being attached to said heatsink carrier.
- 14. The package article in accordance with claim 12, wherein said fiber optic coupling comprises an overmolding.

15. The package article in accordance with claim 12, wherein said fiber optic coupling comprises an optical coupler connected to said optoelectronic die at one end, said optical coupler being attached to an optical connector at an opposite end, said optical connector being connected to said at least one fiber optic cable.

oriented set of fiber optic cables to vertically oriented translating dies, comprising: at least one fiber optic cable, said fiber optic cable being oriented substantially parallel to a plane defining a substantially horizontally oriented laminate, a flexible circuit operatively disposed between said laminate and said at least one fiber optic cable, such that said at least one fiber optic cable, such that said at least one fiber optic cable exits from said laminate in a direction substantially parallel to a horizontal plane defining an orientation of said laminate, an overmold frame that is supported by said laminate, a heatsink carrier with optoelectronic die, said overmold frame having a cavity for receiving said flexible circuit, said optoelectronic die and said heatsink carrier.

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- 1 17. A package article for communicating with a host
 2 card, said package article having a structure in accordance
 3 with claim 16, and being disposed proximate said host card
 4 for transmitting electronic signals therebetween.
 - 18. The package article in accordance with claim 16, further comprising at least one RF barrier shield, said overmold frame housing said at least one RF barrier shield for RF isolation of said at least one optoelectronic die.
 - 19. The package article in accordance with claim 16, further comprising a fiber optic coupling disposed between said at least one optoelectronic die and said at least one fiber optic cable.
 - 20. The package article in accordance with claim 19, further comprising a retainer, and wherein said fiber optic coupling disposed between said at least one optoelectronic die and said at least one fiber optic cable is removably secured to said retainer, said retainer being attached to said heatsink carrier.
- 21. The package article in accordance with claim 19,
 wherein said fiber optic coupling comprises an overmolding.

1	22. The package article in accordance with claim 19,
2	wherein said fiber optic coupling comprises an optical
3	coupler connected to said optoelectronic die at one end,
4	said optical coupler being attached to an optical connector
5	at an opposite end, said optical connector being connected
5	to said at least one fiber optic cable.

23. A transmitting optoelectric subassembly for accepting a parallel fiber optic connector that is secured to one end of a parallel fiber optic cable, comprising:

an optoelectronic subassembly comprising a transmitting optoelectronic device secured to a carrier, an electrical signal transfer device, and an optical coupler signal transfer device secured to a retainer and to said carrier; and

an/electronic subassembly comprising an overmold frame secured to a laminate and to said retainer.

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24. The package in accordance with claim 23, wherein
said electrical signal transfer device electronically
couples an electronic signal from said laminate to said
transmitting optoelectron c device, said transmitting
optoelectronic device converts said electronic signal to an
optical signal, said optical signal transfer device
optically couples said optical signal to said parallel fiber
optic connector, and said retainer removably retains said
parallel fiber optic connector.

1	25. An electronic package subassembly for electrically		
2	coupling to an external contact pad array disposed on a host		
3	electronic base, said electronic package subassembly		
4	disposed to mechanically and electrically accept an external		
5	electronic component, said electronic package subassembly		
6	comprising:		
7	an electronic device secured to a laminate		
8	having a first contact pad array for		
9	electrically coupling to said external contact pad		
10	array, a second contact pad array for electrically		
11	coupling to said external electronic component,		
12	and laminate wiring for electrically coupling said		

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an overmold frame having an encasement portion that substantially encapsulates said electronic device and alignment means for accepting said external electronic component.

first contact pad array to said second contact pad

array and to said electronic device; and

An electronic package subassembly electrically

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electronic component;

19	wherein said electronic device is secured to said
20	second laminate surface and encased substantially within
21	said encasement portion.
1	27. A method for coupling at least one fiber optic
9 ¹ 2	cable to at least one translating die, comprising:
/	
3	applying an electrical signal from an amplifier
4	die to a fexible circuit disposed on a laminate to
5	which a host card is electrically connected;
6	converting said electrical signal to an optical
7	signal; and
8	applying said optical signal to an optical coupler
9	for transmitting said optical signal to an optical

cable.

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donnector attached to said at least one fiber optic

	2	cable to at least one translating die in accordance with
	3	claim 27, the steps further comprising:
	4	removing heat from an optoelectronic die used in
	5	said electrical signal converting step.
		29. The method for coupling at least one fiber optic cable to at least one translating die in accordance with claim 28, the steps further comprising:
W. W.	4	providing a heatsink carrier operatively connected
firm firm firm firm	5	to said at least one translating die for performing
ions at at our tours the source of the sourc	6	said heat removing step.

The method for coupling at least one fiber optic

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L	30. The method for coupling at 1	least one fiber optio
?	cable to at least one translating die	in accordance with
3	claim 27, the steps further comprising	i :

providing a retainer operatively connected to said optical coupler and removably connected to said optical connector for aligning said optical coupler with said at least one fiber optic cable of said optical connector.